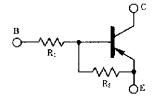
COMPOUND TRANSISTOR

on-chip resistor NPN silicon epitaxial transistor For mid-speed switching

FEATURES

NEC

- High current drives such as IC and motor solenoid available up to 2 A
- On-chip bias resistor
- · Low power consumption during drive



AQ1 SERIES LISTS

Products	R1 (KΩ)	R₂ (KΩ)
AQ1L2N	0.47	1.0
AQ1A3M	1.0	1.0
AQ1F3M	2.2	2.2
AQ1F3P	2.2	10
AQ1L2Q	0.47	4.7
AQ1F2Q	0.22	2.2
AQ1A4A	_	10

PACKAGE DRAWING (UNIT: mm)

Electrode Co	onnectio	on
1. Emitter	EIAJ	: SC-43B
2. Collector	JEDE	C: TO-92
2 Page		· DA00

ABSOLUTE MAXIMUM RATINGS (Ta = 25°C)

Parameter	Symbol	Ratings	Unit
Collector to base voltage	Vсво	-20	V
Collector to emitter voltage	VCEO	-20	V
Emitter to base voltage	VEBO	-10	V
Collector current (DC)	IC(DC)	-2.0	А
Collector current (Pulse)	IC(pulse) *	-3.0	А
Base current (DC)	B(DC)	-0.04	А
Total power dissipation	Рт	750	mW
Junction temperature	Tj	150	°C
Storage temperature	Tstg	–55 to +150	°C

* PW \leq 10 ms, duty cycle \leq 50 %

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AQ1L2N ELECTRICAL CHARACTERISTICS (Ta = 25°C)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Collector cutoff current	Ісво	$V_{CB} = -20 \text{ V}, \text{ I}_{E} = 0$			100	nA
DC current gain	hfe1 **	$V_{CE} = -2.0 \text{ V}, \text{ Ic} = -0.1 \text{ A}$	50			-
DC current gain	hfe2 **	Vce = -2.0 V, Ic = -1.0 A	150			_
DC current gain	hfe3 **	Vce = -2.0 V, Ic = -2.0 A	50			_
Low level output voltage	V _{CE(sat)} **	Ic = -5.0 A, Ic = -0.7 A			-0.55	V
Low level input voltage	VIL **	$V_{CE} = -5.0 \text{ V}, \text{ Ic} = -100 \ \mu\text{A}$			-0.3	V
Input resistance	R1		329	470	611	Ω
E-to-B resistance	R2		0.7	1.0	1.3	kΩ

** PW \leq 350 μ s, duty cycle \leq 2 %

AQ1A3M ELECTRICAL CHARACTERISTICS (Ta = 25°C)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Collector cutoff current	Ісво	$V_{CB} = -20 V$, $I_E = 0$			-100	nA
DC current gain	hfe1 **	$V_{CE} = -2.0 \text{ V}, \text{ Ic} = -0.1 \text{ A}$	50			-
DC current gain	hFE2 **	V _{CE} = -2.0 V, I _C = -1.0 A	150			_
DC current gain	hfe3 **	$V_{CE} = -2.0 \text{ V}, \text{ Ic} = -2.0 \text{ A}$	50			-
Low level output voltage	Vol **	Ic = -5.0 A, Ic = -0.5 A			-0.4	V
Low level input voltage	Vı∟ **	$V_{CE} = -5.0 \text{ V}, \text{ Ic} = -100 \ \mu\text{A}$			-0.3	V
Input resistance	R1		0.7	1.0	1.3	kΩ
E-to-B resistance	R2		0.7	1.0	1.3	kΩ

** PW \leq 350 μ s, duty cycle \leq 2 %

AQ1F3M

ELECTRICAL CHARACTERISTICS (Ta = 25°C)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Collector cutoff current	Ісво	$V_{CB} = -20 \text{ V}, \text{ I}_{E} = 0$			100	nA
DC current gain	hfe1 **	$V_{CE} = -2.0 \text{ V}, \text{ Ic} = -0.1 \text{ A}$	80			-
DC current gain	hfe2 **	$V_{CE} = -2.0 \text{ V}, \text{ Ic} = -1.0 \text{ A}$	150			-
DC current gain	hfe3 **	$V_{CE} = -2.0 \text{ V}, \text{ Ic} = -2.0 \text{ A}$	50			-
Low level output voltage	Vol **	Ic = -5.0 A, Ic = -0.3 A			-0.3	V
Low level input voltage	VIL **	$V_{CE} = -5.0 \text{ V}, \text{ Ic} = -100 \ \mu\text{A}$			-0.3	V
Input resistance	R1		1.54	2.2	2.86	kΩ
E-to-B resistance	R₂		1.54	2.2	2.86	kΩ

** PW \leq 350 μ s, duty cycle \leq 2 %

AQ1F3P ELECTRICAL CHARACTERISTICS (Ta = 25°C)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Collector cutoff current	Ісво	$V_{CB} = -20 \text{ V}, \text{ Ie} = 0$			-100	nA
DC current gain	hfe1 **	$V_{CE} = -2.0 \text{ V}, \text{ Ic} = -0.1 \text{ A}$	200			-
DC current gain	hfe2 **	$V_{CE} = -2.0 \text{ V}, \text{ Ic} = -1.0 \text{ A}$	150			-
DC current gain	hfe3 **	$V_{CE} = -2.0 \text{ V}, \text{ Ic} = -2.0 \text{ A}$	50			I
Low level output voltage	V OL **	Ic = -5.0 A, Ic = -0.3 A			-0.3	V
Low level input voltage	VIL **	$V_{CE} = -5.0 \text{ V}, \text{ Ic} = -100 \ \mu\text{A}$			-0.3	V
Input resistance	R1		1.54	2.2	2.86	kΩ
E-to-B resistance	R2		7	10	13	kΩ

** PW \leq 350 μ s, duty cycle \leq 2 %

AQ1L2Q

ELECTRICAL CHARACTERISTICS (Ta = 25°C)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Collector cutoff current	Ісво	$V_{CB} = -20 \text{ V}, \text{ I}_{E} = 0$			-100	nA
DC current gain	hfe1 **	$V_{CE} = -2.0 \text{ V}, \text{ Ic} = -0.1 \text{ A}$	150			-
DC current gain	hfe2 **	Vce = -2.0 V, lc = -1.0 A	150			_
DC current gain	hfe3 **	$V_{CE} = -2.0 \text{ V}, \text{ Ic} = -2.0 \text{ A}$	50			-
Low level output voltage	V OL **	Ic = −5.0 A, Ic = −0.7 A			-0.55	V
Low level input voltage	VIL **	$V_{CE} = -5.0 \text{ V}, \text{ Ic} = -100 \ \mu\text{A}$			-0.3	V
Input resistance	R1		329	470	611	Ω
E-to-B resistance	R2		3.29	4.7	6.11	kΩ

** PW \leq 350 μ s, duty cycle \leq 2 %

AQ1F2Q ELECTRICAL CHARACTERISTICS (Ta = 25°C)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Collector cutoff current	Ісво	$V_{CB} = -20 \text{ V}, I_E = 0$			-100	nA
DC current gain	hfe1 **	Vce = -2.0 V, lc = -0.1 A	80			-
DC current gain	hfe2 **	$V_{CE} = -2.0 \text{ V}, \text{ Ic} = -1.0 \text{ A}$	150			-
DC current gain	hfe3 **	Vce = -2.0 V, Ic = -2.0 A	50			-
Low level output voltage	Vol **	Ic = −5.0 A, Ic = −0.7 A			-0.55	V
Low level input voltage	VIL **	$V_{CE} = -5.0 \text{ V}, \text{ Ic} = -100 \ \mu\text{A}$			-0.3	V
Input resistance	R1		154	220	286	Ω
E-to-B resistance	R₂		1.54	2.2	2.86	kΩ

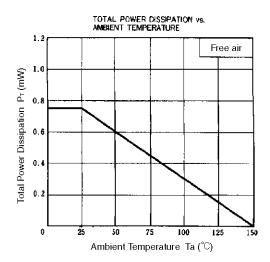
** PW \leq 350 μ s, duty cycle \leq 2 %

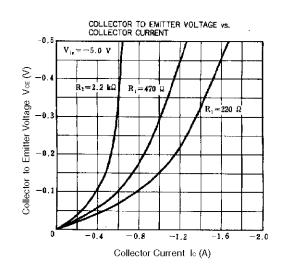
AQ1A4A ELECTRICAL CHARACTERISTICS (Ta = 25°C)

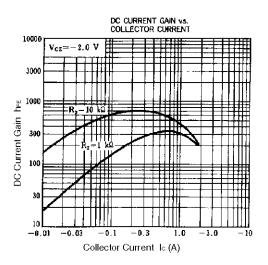
Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Collector cutoff current	Ісво	$V_{CB} = -20 V, I_E = 0$			-100	nA
DC current gain	hfe1 **	$V_{CE} = -2.0 \text{ V}, \text{ Ic} = -0.1 \text{ A}$	200			-
DC current gain	hfe2 **	$V_{CE} = -2.0 \text{ V}, \text{ Ic} = -1.0 \text{ A}$	150			-
DC current gain	hfe3 **	$V_{CE} = -2.0 \text{ V}, \text{ Ic} = -2.0 \text{ A}$	50			-
Collector saturation voltage	Vol **	Ic = −1.0 A, Ic = −20 mA		-0.35	-0.45	V
Low level input voltage	VIL **	$V_{CE} = -5.0 \text{ V}, \text{ Ic} = -100 \ \mu\text{A}$			-0.3	V
Input resistance	Rı		-	_	-	Ω
E-to-B resistance	R2		7	10	13	kΩ

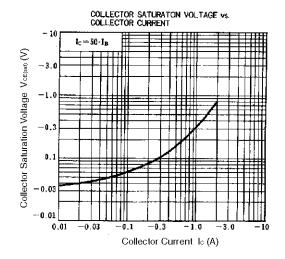
** PW \leq 350 μ s, duty cycle \leq 2 %

TYPICAL CHARACTERISTICS (Ta = 25°C)









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